What is claimed is:

1. A thermal fuse comprising:

a fusible alloy including tin;

a couple of lead conductors connected to both ends of said fusible alloy, respectively; and

surface layers made of metal including tin provided on said lead conductors, respectively, said surface layers having thicknesses not greater than 14μm.

2. The thermal fuse according to claim 1, wherein said surface layers are made of tin.

3. The thermal fuse according to claim 1, wherein said surface layers include silver.

4. The thermal fuse as defined in claim 3, wherein said surface layers include copper.

5. The thermal fuse according to claim 4, wherein said surface layers include bismuth.

6. The thermal fuse according to claim 1, wherein said surface layers include copper.

7. The thermal fuse according to claim 1, wherein said surface layers include bismuth.

8. The thermal fuse according to claim 1, wherein said surface layers have composition having no orientation.

9. The thermal fuse according to claim 1, wherein said thicknesses of said surface layers are not less than 1μm.

10. A method of manufacturing a thermal fuse, comprising the steps of:

preparing a fusible alloy including tin, and a couple of lead conductors having surface layers formed thereon, respectively, the surface conductors being made of metal including tin and having thicknesses not greater than 14μm; and

connecting the lead conductors to both ends of the fusible alloy, respectively.

11. The method according to claim 10, wherein the surface layers are made of tin.

12. The method according to claim 10, wherein the surface layers include silver.

13. The method according to according to claim 12, wherein the surface layers include copper.

14. The method according to claim 13, wherein the surface layers include bismuth.

15. The method according to claim 10, wherein the surface layers

include copper.

16. The method according to claim 10, wherein the surface layers include bismuth.

17. The method according to claim 10, wherein the surface layers have composition having no orientation.

18. The method according to in claim 10, wherein the thicknesses of the surface layers are not less than 1μm.